

Correction to Uniform and Ordered Copper Nanomeshes by Microsphere Lithography for Transparent Electrodes

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Figure 3 in our paper should be the following, instead of the Table of Contents image.

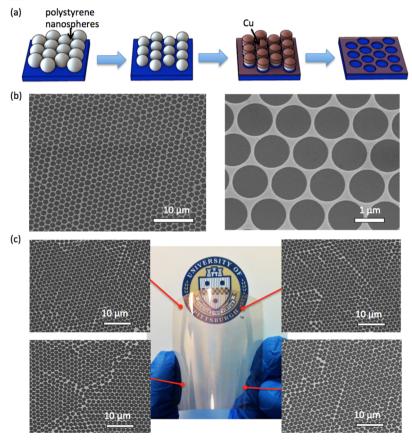


Figure 3. (a) Schematic of the Cu NM fabrication process. (b) Scanning electron microscopy (SEM) images of fabricated Cu NM with a = 1300 nm, w = 150 nm, and t = 40 nm on a rigid substrate. (c) Optical image of a Cu NM fabricated directly on a flexible polyethylene terephthalate (PET) substrate. SEM images show the Cu NM at four various locations.